

Low-Power, Two-Port, High-Speed, USB2.0 (480 Mbps) UART Switch

FSUSB42

Description

The FSUSB42 is a bi-directional, low-power, two-port, high-speed, USB2.0 switch. Configured as a double-pole, double-throw switch (DPDT) switch, it is optimized for switching between any combination of high-speed (480 Mbps) or Full-Speed (12 Mbps) sources.

The FSUSB42 is compatible with the requirements of USB2.0 and features an extremely low on capacitance (CON) of 3.7 pF. The wide bandwidth of this device (720 MHz) exceeds the bandwidth needed to pass the third harmonic, resulting in signals with minimum edge and phase distortion. Superior channel—to—channel crosstalk also minimizes interference.

The FSUSB42 contains special circuitry on the switch I/O pins for applications w here the V_{CC} supply is powered—of f (V_{CC} = 0 V), which allow s the device to withstand an over–voltage condition. This device is designed to minimize current consumption even when the control voltage applied to the SEL pin is low er than the supply voltage (V_{CC}). This feature is especially valuable to ultra–portable applications, such as cell phones, allowing for direct interface with the general–purpose I/Os of the baseband processor. Other applications include switching and connector sharing in portable cell phones, PDAs, digital cameras, printers, and notebook computers.

Features

- Low On Capacitance: 3.7 pF Typical
- Low On Resistance: 3.9 Ω Typical
- Low Pow er Consumption: 1 μA Maximum
 - 15 μA Maximum I_{CCT} over an Expanded Voltage Range (V_{IN} = 1.8 V, V_{CC} = 4.4 V)
- Wide -3 db Bandwidth: > 720 MHz
- Packaged in:
 - 10-Lead UMLP (1.4 x 1.8 mm)
 - ◆ 10-Lead MSOP
- 8 kV ESD Rating, >16 kV Power / GND ESD Rating
- Over-Voltage Tolerance (OVT) On All USB Ports Up to 5.25 V without External Components

Typical Applications

- Cell Phone, PDA, Digital Camera, and Notebook
- LCD Monitor, TV, and Set-Top Box

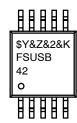




UQFN10 1.4 × 1.8, 0.4 P CASE 523BC MSOP10 CASE 846AP

MARKING DIAGRAMS





HE, FSUCB42 = Specific Device Code

\$Y = onsemi Logo

&K = 2 Digit Lot Run Traceability Code

&2 = 2-Digit Date Code &Z = Assembly Location

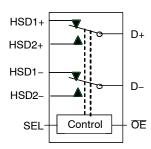
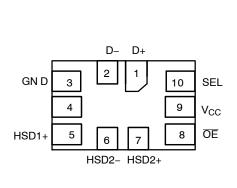


Figure 1. Analog Symbol

ORDERING INFORMATION

See detailed ordering and shipping information on page 7 of this data sheet.

Pin Assignments



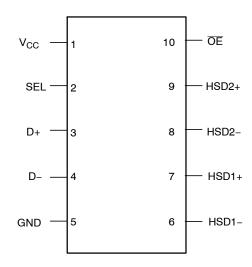


Figure 2. 10-Lead UMLP (Top-Through View)

Figure 3. 10-Lead MSOP (Top-Through View)

PIN DESCRIPTION

UMLP Pin#	MSOP Pin#	Name	Description
1	3	D+	Common USB Data Bus
2	4	D-	Common USB Data Bus
3	5	GND	Ground
4	6	HSD1-	Multiplexed Source Input 1
5	7	HSD1+	Multiplexed Source Input 1
6	8	HSD2-	Multiplexed Source Input 2
7	9	HSD2+	Multiplexed Source Input 2
8	10	ŌĒ	Switch Enable
9	1	V _{CC}	Supply Voltage
10	2	SEL	Switch Select

TRUTH TABLE

SEL	ŌE	Function
X	HIGH	Disconnect
LOW	LOW	D+ = HSD1+, D- = HSD1-
HIGH	LOW	D+ = HSD2+, D- = HSD2-

- LOW ≤ V_{IL}.
 HIGH ≤ V_{IH}.
 X = Don't Care.

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter			Max	Unit
V _{CC}	Supply Voltage		-0.5	5.6	V
V _{CNTRL}	DC Input Voltage (S, OE) (Note 4)		-0.5	V _{CC}	V
V _{SW}	DC Switch I/O Voltage (Note 4) (VCC	C = 0 V)	-0.50	5.25	V
I _{IK}	DC Input Diode Current		-50	_	mA
I _{OUT}	DC Output Current	DC Output Current		100	mA
T _{STG}	Storage Temperature		-65	+150	°C
MSL	Moisture Sensitivity Level (JEDEC J-	Moisture Sensitivity Level (JEDEC J-STD-020A)		1	Level
ESD	Human Body Model, JEDEC:	All Pins	7	-	kV
	JESD22-A114	I/O GND	8	-	
		Power to GND	16	_	
		D+/D-	9	_	
	IEC 61000-4-2 System on USB	Air Discharge	15	-	
	Connector Pins D+ & D-	Contact	8	-	1
	Charged Device Model, JEDEC: JES	D22-C101	2	-	1

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Max	Unit
V _{CC}	Supply Voltage	2.4	4.4	V
V _{CNTRL}	Control Input Voltage (S, OE) (Note 5)	0	V _{CC}	V
V _{SW}	Switch I/O Voltage		4.5	V
T _A	Operating Temperature	-40	+85	°C

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

DC ELECTRICAL CHARACTERISTICS

(All typical value are at $T_A = 25^{\circ}C$ unless otherwise specified.)

				T _A = -	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$		
Symbol	Parameter	Condition	V _{CC} (V)	Min	Тур	Max	Unit
V _{IK}	Clamp Diode Voltage	I _{IN} = 18 mA	3.0	_	-	-1.2	V
V_{IH}	Input Voltage High		2.4 to 3.6	1.3	-	-	V
			4.3	1.7	-	-	1
V _{IL}	Input Voltage Low		2.4 to 3.6	_	-	0.5	V
			4.3	_	-	0.7	
I _{IN}	Control Input Leakage	V _{SW} = 0 to V _{CC}	0 to 4.3	-1	-	1	μΑ
loz	Off State Leakage	0 ≤ Dn, HSD1n, HSD2n ≤ 3.6 V	4.3	-2	-	2	μΑ
l _{OFF}	Power-Off Leakage Current (All I/O Ports)	V _{SW} = 0 V to 4.3 V, V _{CC} = 0 V Figure 5	0	-2	-	2	μΑ
R _{ON}	HS Switch On Resistance	V _{SW} = 0.4 V, I _{ON} =8 mA	2.4	_	4.5	7.5	Ω
	(Note 6)	Figure 4	3.0	_	3.9	6.5	
ΔR_{ON}	HS Delta R _{ON} (Note 7)	V _{SW} = 0.4, I _{ON} = 8 mA	3.0	_	0.65	-	Ω
I _{CC}	Quiescent Supply Current	V _{CNTRL} = 0 or V _{CC} , I _{OUT} = 0	4.3	-	-	1	μΑ

^{4.} The input and output negative ratings may be exceeded if the input and output diode current ratings are observed.

^{5.} The control input must be held HIGH or LOW and it must not float.

DC ELECTRICAL CHARACTERISTICS (continued)

(All typical value are at $T_A = 25^{\circ}C$ unless otherwise specified.)

				T _A = -40°C to +85°C			
Symbol	Parameter	Condition	V _{CC} (V)	Min	Тур	Max	Unit
I _{CCT}	Increase in I _{CC} Current per	V _{CNTRL} = 2.6, V _{CC} = 4.3 V	4.3	-	-	10	μΑ
	Control Voltage and V _{CC}	V _{CNTRL} = 1.8, V _{CC} = 4.3 V	4.3		-	15	μΑ

^{6.} Measured by the voltage drop between HSDn and Dn pins at the indicated current through the switch. On resistance is determined by the lower of the voltage on the two (HSDn or Dn ports).

AC ELECTRICAL CHARACTERISTICS

(All typical value are for V_{CC} = 3.3 V at T_A = 25°C unless otherwise specified.)

				$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$			
Symbol	Parameter	Condition	V _{CC} (V)	Min	Тур	Max	Unit
t _{ON}	Turn-On Time	$R_L = 50 \Omega$, $C_L = 5 pF$, $V_{SW} = 0.8 V$,	2.4	-	24	40	ns
	S, OE to Output	Figure 6, Figure 7	3.0 to 3.6	-	13	30	
t _{OFF}	Turn-Off Time	$R_L = 50 \Omega$, $C_L = 5 pF$, $V_{SW} = 0.8 V$,	2.4	-	15	35	ns
	S, OE to Output	Figure 6, Figure 7	3.0 to 3.6	-	12	25	
t _{PD}	Propagation Delay (Note 8)	$C_L = 5 \text{ pF}, R_L = 50 \Omega,$ Figure 6, Figure 8	3.3	-	0.25	-	ns
t _{BBM}	Break-Before-Make	$R_L = 50 \Omega$, $C_L = 5 pF$,	2.4	2.0	-	10	ns
		V _{SW1} = V _{SW2} = 0.8 V, Figure 10	3.0 to 3.6	2.0	-	6.5	
O _{IRR}	Off Isolation	R_L = 50 Ω , f = 240 MHz, Figure 12	3.0 to 3.6	-	-30	-	dB
Xtalk	Non-Adjacent Channel Crosstalk	$R_L = 50 \Omega$, f = 240 MHz, Figure 13	3.0 to 3.6	-	-45	_	dB
BW	-3 db Band Width	R_L = 50 Ω , C_L = 0 pF, Figure 11	3.0 to 3.6	-	720	-	MHz
		$R_L = 50 \Omega$, $C_L = 5 pF$, Figure 11		-	550	-	MHz

^{8.} Guaranteed by characterization.

USB HIGH-SPEED-RELATED AC ELECTRICAL CHARACTERISTICS

(All typical value are for V_{CC} = 3.3 V at T_A = 25°C unless otherwise specified.)

				$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$			
Symbol	Parameter	Condition	V _{CC} (V)	Min	Тур	Max	Unit
t _{SK(P)}	Skew of Opposite Transition of the Same Output (Note 9)	$C_L = 5 \text{ pF}, R_L = 50 \Omega, \text{ Figure 9}$	-	-	20	-	ps
tı	Total Jitter (Note 9)	$R_L = 50 \ \Omega, C_L = 5 \ pF,$ $t_R = t_F = 500 \ ps \ (10-90\%) \ at$ $480 \ Mbps \ (PRBS = 2^{15} - 1)$	-	-	200	-	ps

^{9.} Guaranteed by characterization.

CAPACITANCE

			T _A = -40°C to +85°C			
Symbol	Parameter	Condition	Min	Тур	Max	Unit
C _{IN}	Control Pin Input Capacitance	V _{CC} = 0 V	-	1.5	-	pF
C _{ON}	D+/D- On Capacitance	V _{CC} = 3.3 V, OE = 0 V, f = 240 MHz, Figure 15	-	3.7	-	pF
C _{OFF}	D1n, D2n Off Capacitance	V _{CC} and $\overline{\text{OE}}$ = 3.3 V, Figure 14	-	2.0	-	pF

^{7.} Guaranteed by characterization.

Test Diagrams

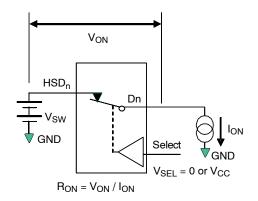
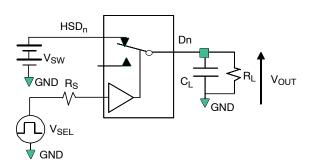


Figure 4. On Resistance



 R_L , R_S , and C_L are functions of the application environment (see AC Tables for specific values) C_L includes test fixture and stray capacitance.

Figure 6. AC Test Circuit Load

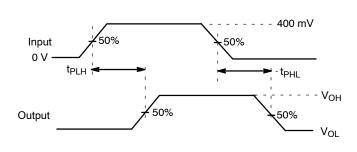
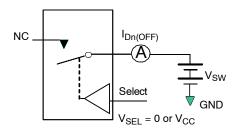


Figure 8. Propagation Delay (t_Rt_F - 500 ps)



**Each switch port is tested separately

Figure 5. Off Leakage

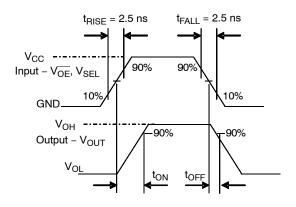


Figure 7. Turn-On / Turn-Off Waveforms

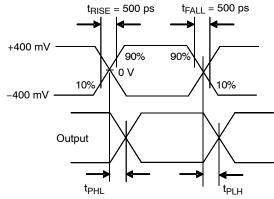


Figure 9. Intra-Pair Skew Test t_{SK(P)}

Test Diagrams (continued)

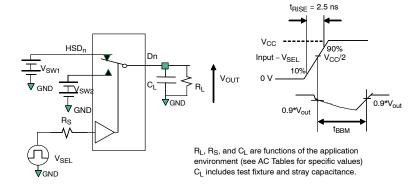


Figure 10. Break-Before-Make Interval Timing

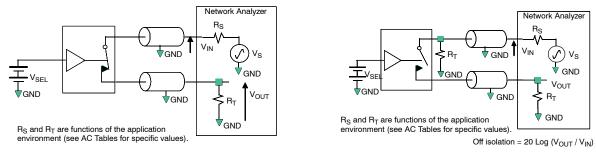


Figure 11. Bandwidth

Figure 12. Channel Off Isolation

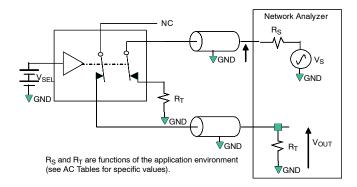


Figure 13. Non-Adjacent Channel-to-Channel Crosstalk

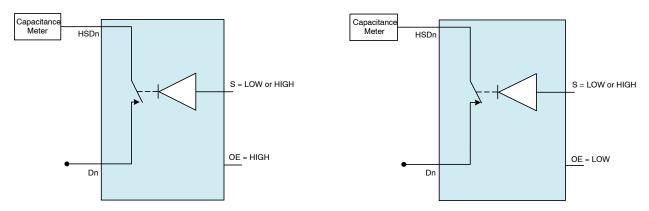


Figure 14. Channel Off Capacitance

Figure 15. Channel On Capacitance

ORDERING INFORMATION

Part Number	Device Code	Operating Temperature Range	Package	Shipping [†]
FSUSB42UMX	HE	−40 to 85°C	10-Lead, Quad, Ultrathin Molded Leadless Package (UQFN10), 1.4 × 1.8 mm	5000 / Tape and Reel
FSUSB42MUX	FSUSB42	−40 to 85°C	10-Lead, Molded Small-Outline Package (MSOP) JEDEC MO-187, 3.0 mm Wide	4000 / Tape and Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.



 \triangle 0.05 C

PIN 1

REFERENCE

C



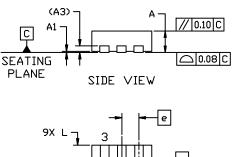
UQFN10 1.4x1.8, 0.4P CASE 523BC **ISSUE B**

DATE 13 MAY 2022

NOTES:

- DIMENSIONING AND **TOLERANCING** PER ASME Y14.5, 2018
- DIMENSIONS 2. ARE ΙN Al I **MILLIMETERS**
- DIMENSION 6 APPLIES TO PLATED MEASURED TERMINALS AND ΙS BETWEEN 0.15mm AND 0.30mm FROM THE TERMINAL TIP.
- COPLANARITY **APPLIES** TΠ THE EXPOSED PAD AS WELL AS THE **TERMINALS**

DIM	MI	MILLIMETERS				
ויודת	MIN.	N□M.	MAX.			
Α	0.45	0.50	0.55			
A1	0.00	0.025	0.05			
A3	0.	152 REF				
b	0.15	0.20	0.25			
D	1.35	1.40	1,45			
Е	1.75	1.80	1.85			
е	0.40 BSC					
L	0.35	0.40	0.45			

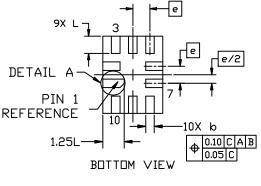


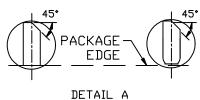
TOP VIEW

 $-\mathbb{B}$

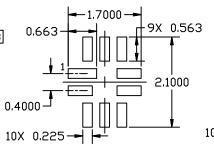
 \triangle 0.05 C

2X

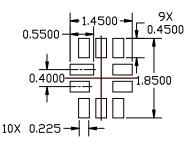




DETIDINAL CONSTRUCTIONS



RECOMMENDED LAND PATTERN



OPTIONAL MINIMIAL TOE LAND PATTERN

RECOMMENDED MOUNTING FOOTPRINT

For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

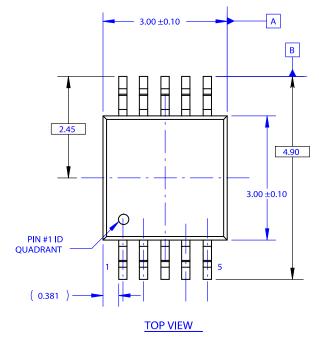
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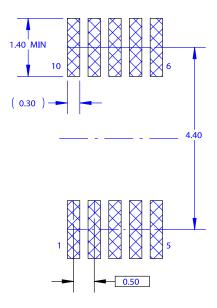
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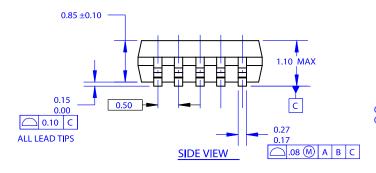


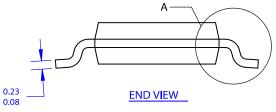
DATE 31 JAN 2017





LAND PATTERN RECOMMENDATION





GAUGE PLANE R0.13 TYP

SEATING PLANE

0.80
0.40
0.95

DETAIL A SCALE 20:1

NOTES: UNLESS OTHERWISE SPECIFIED

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- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR EXTRUSIONS.
- D. DIMENSIONS AND TOLERANCES AS PER ASME
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